

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WEI ZHOU	07/31/2014
ZHAOHUI MA	07/30/2014
AIBIN YU	08/01/2014
RECEIVING PARTY DATA	
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City:	BOISE
State/Country:	IDAHO
Postal Code:	83707-0006
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14451192
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ATTORNEY DOCKET NUMBER:	10829-9116.US00
NAME OF SUBMITTER:	STEPHEN P. WHELAN
SIGNATURE:	/Stephen P. Whelan/
DATE SIGNED:	08/04/2014
Total Attachments: 5 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif source=Assignment#page5.tif	

PATENT

ASSIGNMENT BY INVENTORS

This Assignment is by the following individuals (the "Assignors"):

- Wei Zhou, having a mailing address of Blk. 324C #14-603 Sengkang East Way, Singapore, Republic of Singapore 543324;
- Zhaohui Ma, having a mailing address of Blk. 556 #05-09 Yishun Ave. 6, Singapore, Republic of Singapore 768964; and
- Aibin Yu, having a mailing address of Blk. 659-D #09-337 Jurong West St. 65, Singapore, Republic of Singapore 644659.

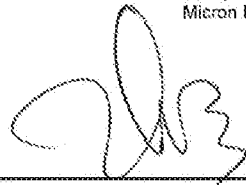
The Assignors invented one or more certain inventions (the "Invention(s)") described in an application for Letters Patent of the United States titled SEMICONDUCTOR DIE ASSEMBLIES WITH HEAT SINK AND ASSOCIATED SYSTEMS AND METHODS, naming the Assignors as inventors, and filed on _____ as U.S. Application No. _____ (the "Application"). The Assignors authorize the Assignee, identified below, or its representatives to insert the application number and filing date of the Application when known.

Micron Technology, Inc., a corporation of Delaware having its principal place of business at 8000 S. Federal Way, P.O. Box 6, Boise, Idaho 83707-0006 ("Assignee"), desires to acquire the entire right, title and interest in and to the Invention(s) and the Application, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in the United States or in any foreign countries.

For valuable consideration, the receipt and sufficiency of which Assignors acknowledge, Assignors hereby sell, assign, and transfer to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Application, and any Patents; any divisions, continuations, and continuations-in-part of the Application and any other application claiming priority rights from the Application; any reissues, reexaminations, or extensions of any and all Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from the Application (collectively, the "Rights"). Assignors warrant that Assignors own the Rights, and

that the Rights are unencumbered. Assignors also agree to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do such additional acts as Assignee deems necessary or desirable to: perfect Assignee's enjoyment of the Rights; conduct proceedings regarding the Rights, including any litigation or interference proceedings; or perfect or defend title to the Rights. Assignors request the Commissioner of Patents to issue any Patent of the United States that may be issued on the Invention(s) to Assignee. This Assignment may be executed in counterparts.


Date: 07/31/2014



Wei Zhou

Witness:

SO CHEE CHUNG
Printed Name



Signature

Witness:

HO KWOK SENG
Printed Name



Signature

Date: July 30, 2014


Zhaochui Ma

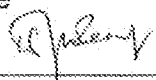
Witness:

SO CHEE CHUNG
Printed Name


Signature

Witness:

HO KWOK SENG
Printed Name


Signature

Date: August 01, 2014



Aibin Yu

Witness:

SO CHEE CHUNG

Printed Name



Signature

Witness:

HO KWOK SENG

Printed Name



Signature